



EMB-845M A1.0

Thermal Image Analysis Report

Report No: 04E080020

Release Date: Dec. 27, 2004

2004-12-24

Issue Stamp

Wenyuan Yang

Manager

Rex Chang

Test Engineer

. **Model Name:** EMB-845M

. **Description:** Long – life Mother Board

. **Date:** Dec. 27, 2004

. **Measure Site:** AAEON QE Dept.

. **Issued by:** Rex Chang

. **Equipment:**

1. TVS-100 series by NIPPON AVIONICS CO., LTD.

. **Simulation Environment:**

Temperature: 22.9 degrees C

System Configuration : EMB-845GE A1.0 (BIOS ver: A2.0)

CPU: Intel Pentium 4 / 3.06GHz / FSB 533MHz

Memory: KINGMAX KDL684J44A-60 (DDR-333) / 256MB

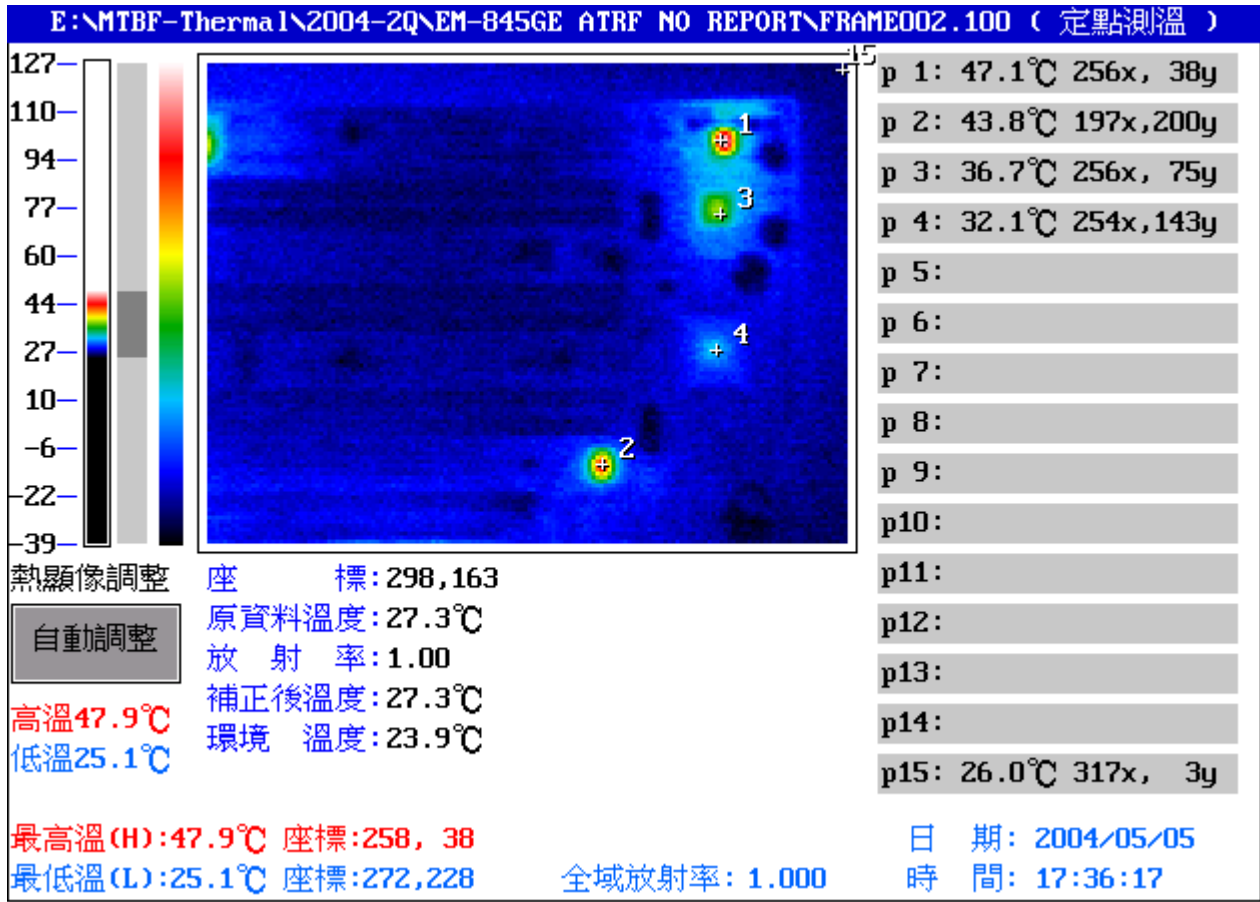
HDD: Seagate ST31276A

Application Software: Windows 2000 run HCT9.5

Take Picture Time: Power on 2 hours after

Temperature Profile Test:

Component Side - 1:



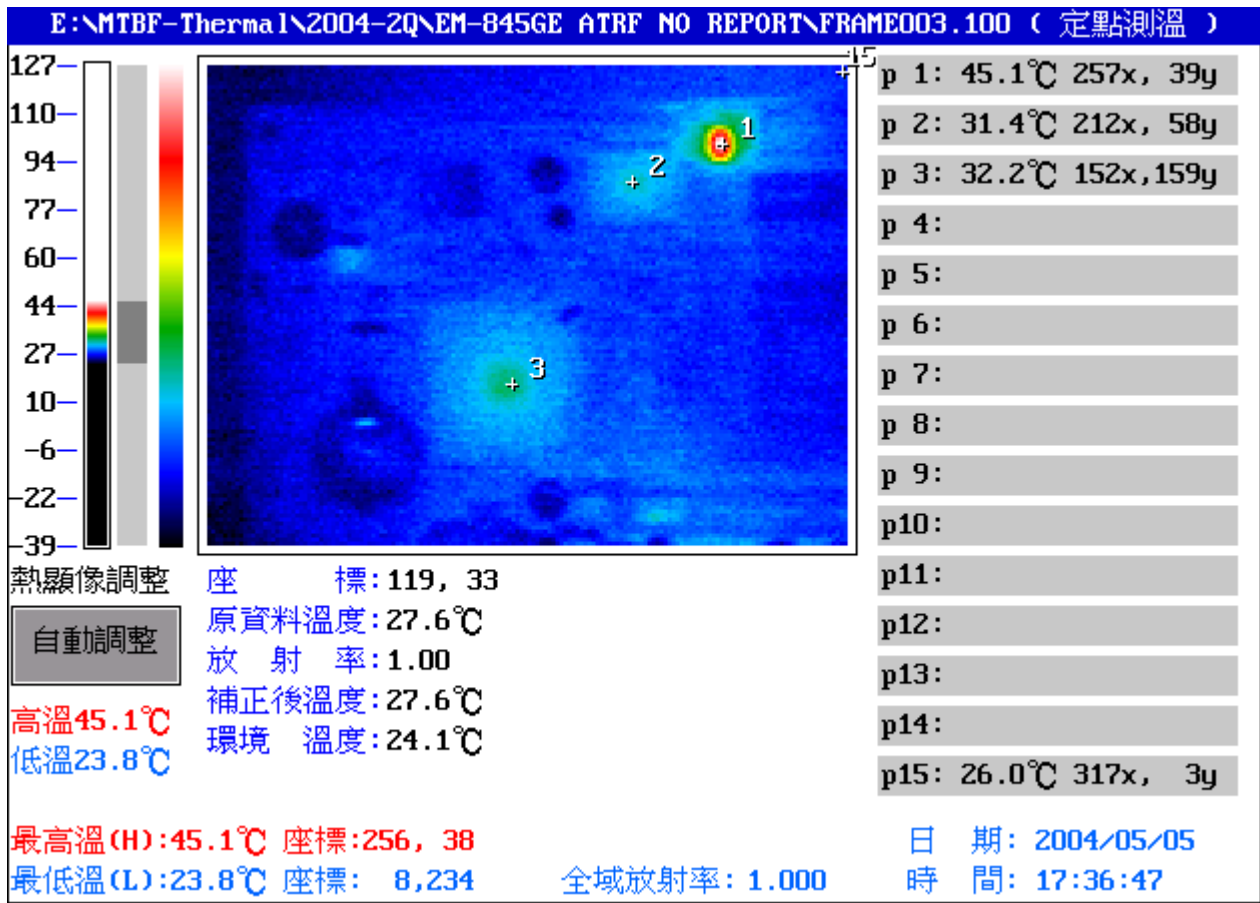
Point	Position	Describe	Ts	Tm	Note
1	U1	LM78L05ACM		47.1	
2	U7	ST75185CTR		43.8	
3	U2	ALC201A		36.7	
4	U4	VIA VT6105LOM		32.1	
5					
6					
7					
8					
9					
10					
11					
12					
13					
14					
15		The Room Temperature		26.0	

1. Operation Temperature ():

Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.

Component Side -2:



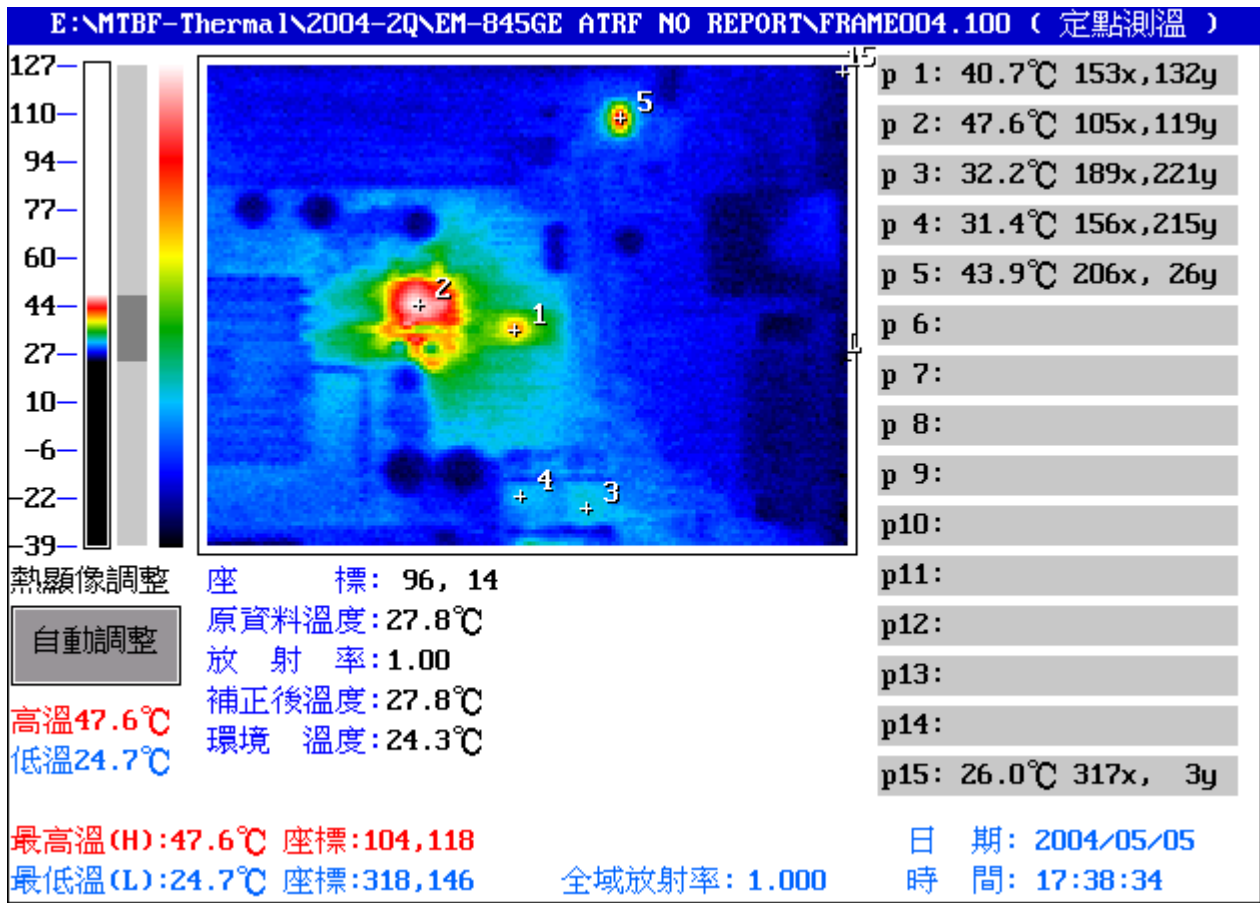
Point	Position	Describe	Ts	Tm	Note
1	U13	ST75185CTR		45.1	
2	U14	ITE IT8712F-A		31.4	
3	U16	Intel FW82801DB		32.2	
4					
5					
6					
7					
8					
9					
10					
11					
12					
13					
14					
15		The Room Temperature		26.0	

1. Operation Temperature ():

Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.

Component Side – 3:



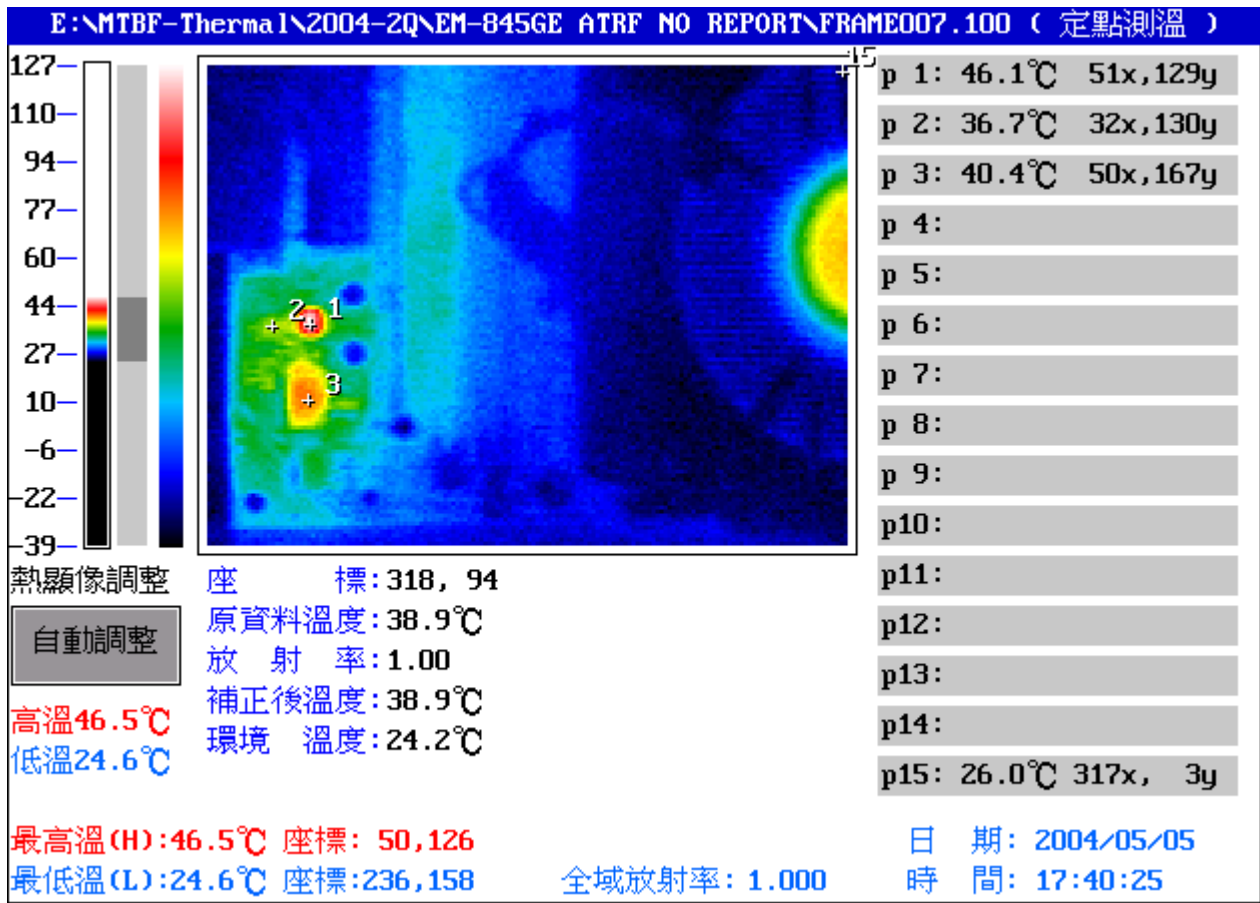
Point	Position	Describe	Ts	Tm	Note
1	U9	RTM360-111R		40.7	
2	Q16	IPB14NO3LA		47.6	
3	Q9	IRF3711S		32.2	
4	Q11	IRF3711S		31.4	
5	U7	ST75185CTR		43.9	
6					
7					
8					
9					
10					
11					
12					
13					
14					
15		The Room Temperature		26.0	

1. Operation Temperature ():

Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.

Component Side – 4:



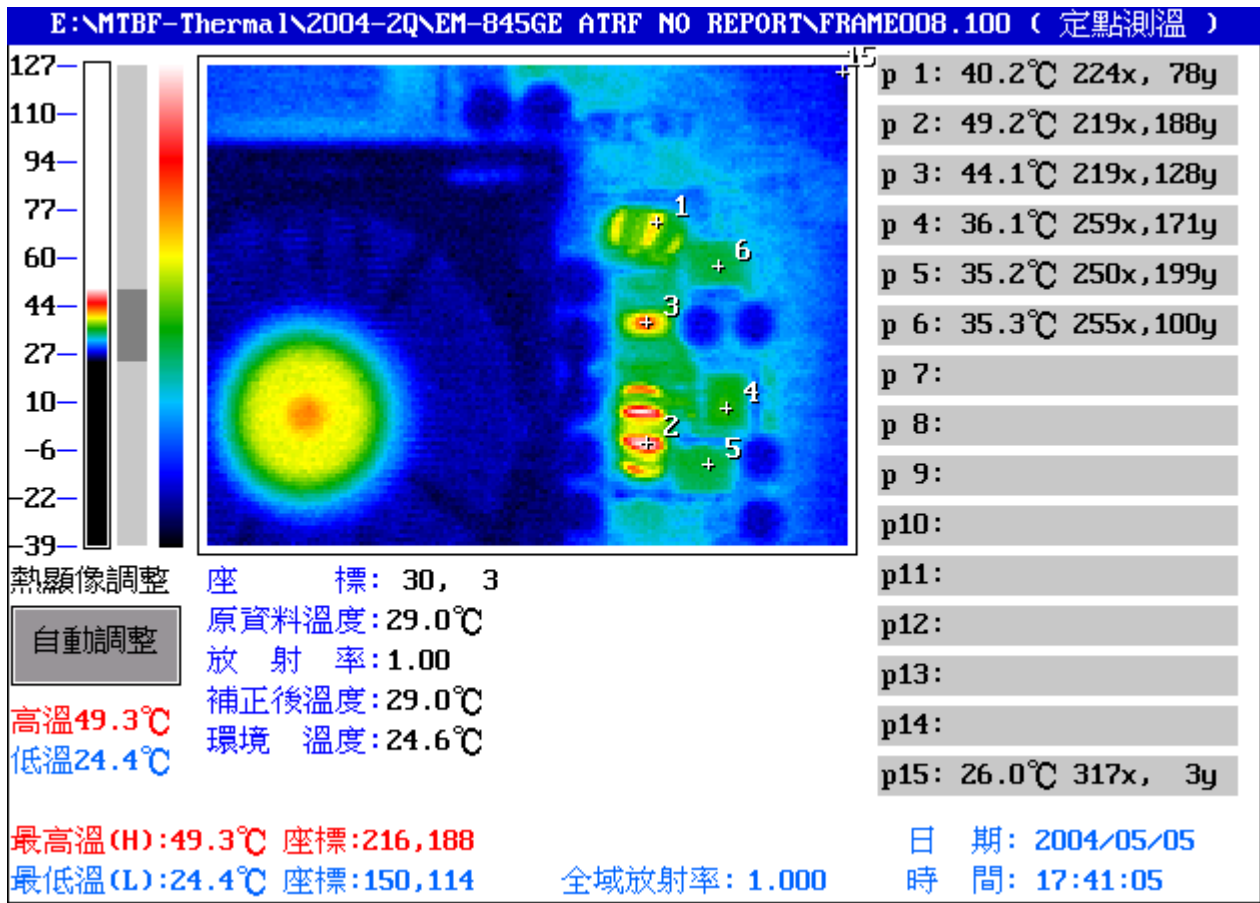
Point	Position	Describe	Ts	Tm	Note
1	U19	RT9173-CS		46.1	
2	U21	RT9174		36.7	
3	Q31	PH020N03L		40.4	
4					
5					
6					
7					
8					
9					
10					
11					
12					
13					
14					
15		The Room Temperature		26.0	

1. Operation Temperature ():

Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.

Component Side – 6:



Point	Position	Describe	Ts	Tm	Note
1	L30	CHOCK COIL 1.1uH 200K/30A		40.2	
2	L31	CHOCK COIL 1.1uH 200K/30A		49.2	
3	U8	HIP66020CD		44.1	
4	Q6	FDB7030BL		36.1	
5	Q7	IRF3711S		35.2	
6	Q5	FDB7030BL		35.3	
7					
8					
9					
10					
11					
12					
13					
14					
15		The Room Temperature		26.0	

1. Operation Temperature ():

Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.